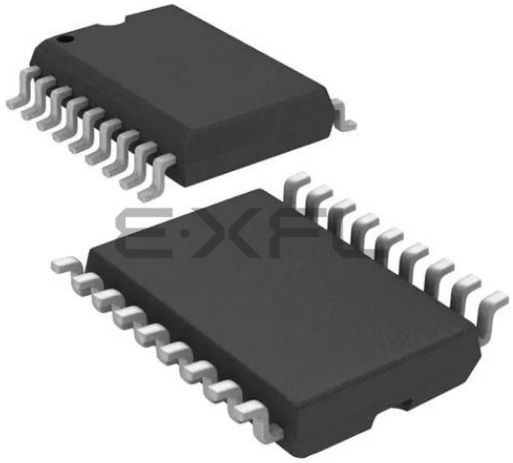


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

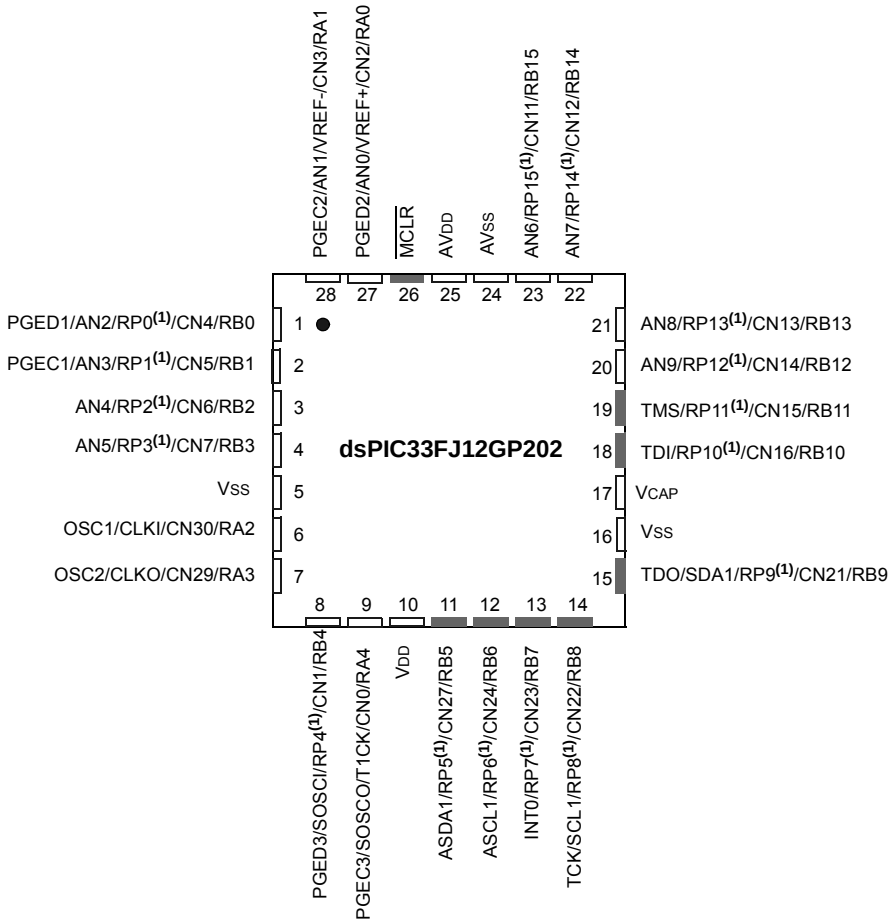
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	12KB (12K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj12gp201-e-so

Pin Diagrams (Continued)

28-Pin QFN(2)

■ = Pins are up to 5V tolerant



Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.

2: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

1.1 Referenced Sources

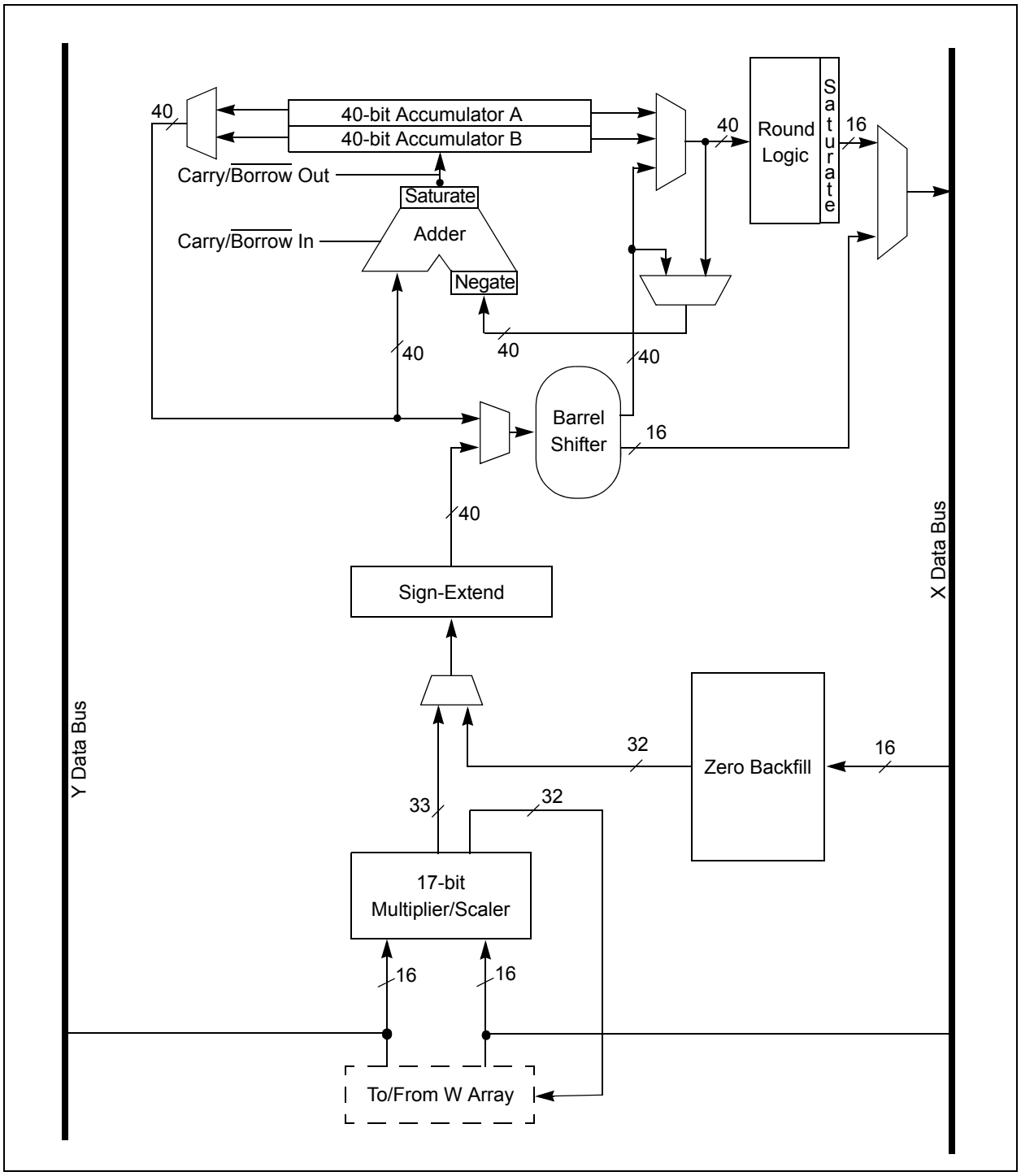
This device data sheet is based on the following individual chapters of the *"dsPIC33F/PIC24H Family Reference Manual"*. These documents should be considered as the general reference for the operation of a particular module or device feature.

Note 1: To access the documents listed below, browse to the documentation section of the dsPIC33FJ12GP202 product page of the Microchip web site (www.microchip.com) or select a family reference manual section from the following list.

In addition to parameters, features, and other documentation, the resulting page provides links to the related family reference manual sections.

- **Section 1. "Introduction"** (DS70197)
- **Section 2. "CPU"** (DS70204)
- **Section 3. "Data Memory"** (DS70202)
- **Section 4. "Program Memory"** (DS70202)
- **Section 5. "Flash Programming"** (DS70191)
- **Section 6. "Interrupts"** (DS70184)
- **Section 7. "Oscillator"** (DS70186)
- **Section 8. "Reset"** (DS70192)
- **Section 9. "Watchdog Timer and Power-saving Modes"** (DS70196)
- **Section 10. "I/O Ports"** (DS70193)
- **Section 11. "Timers"** (DS70205)
- **Section 12. "Input Capture"** (DS70198)
- **Section 13. "Output Compare"** (DS70209)
- **Section 14. "Motor Control PWM"** (DS70187)
- **Section 15. "Quadrature Encoder Interface (QEI)"** (DS70208)
- **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183)
- **Section 17. "UART"** (DS70188)
- **Section 18. "Serial Peripheral Interface (SPI)"** (DS70206)
- **Section 19. "Inter-Integrated Circuit™ (I^2C™)"** (DS70195)

FIGURE 3-3: DSP ENGINE BLOCK DIAGRAM



3.6.2.4 Data Space Write Saturation

In addition to adder/subtracter saturation, writes to data space can also be saturated, but without affecting the contents of the source accumulator. The data space write saturation logic block accepts a 16-bit, 1.15 fractional value from the round logic block as its input, together with overflow status from the original source (accumulator) and the 16-bit round adder. These inputs are combined and used to select the appropriate 1.15 fractional value as output to write to data space memory.

If the SATDW bit in the CORCON register is set, data (after rounding or truncation) is tested for overflow and adjusted accordingly:

- For input data greater than 0x007FFF, data written to memory is forced to the maximum positive 1.15 value, 0x7FFF
- For input data less than 0xFF8000, data written to memory is forced to the maximum negative 1.15 value, 0x8000

The MSb of the source (bit 39) is used to determine the sign of the operand being tested.

If the SATDW bit in the CORCON register is not set, the input data is always passed through unmodified under all conditions.

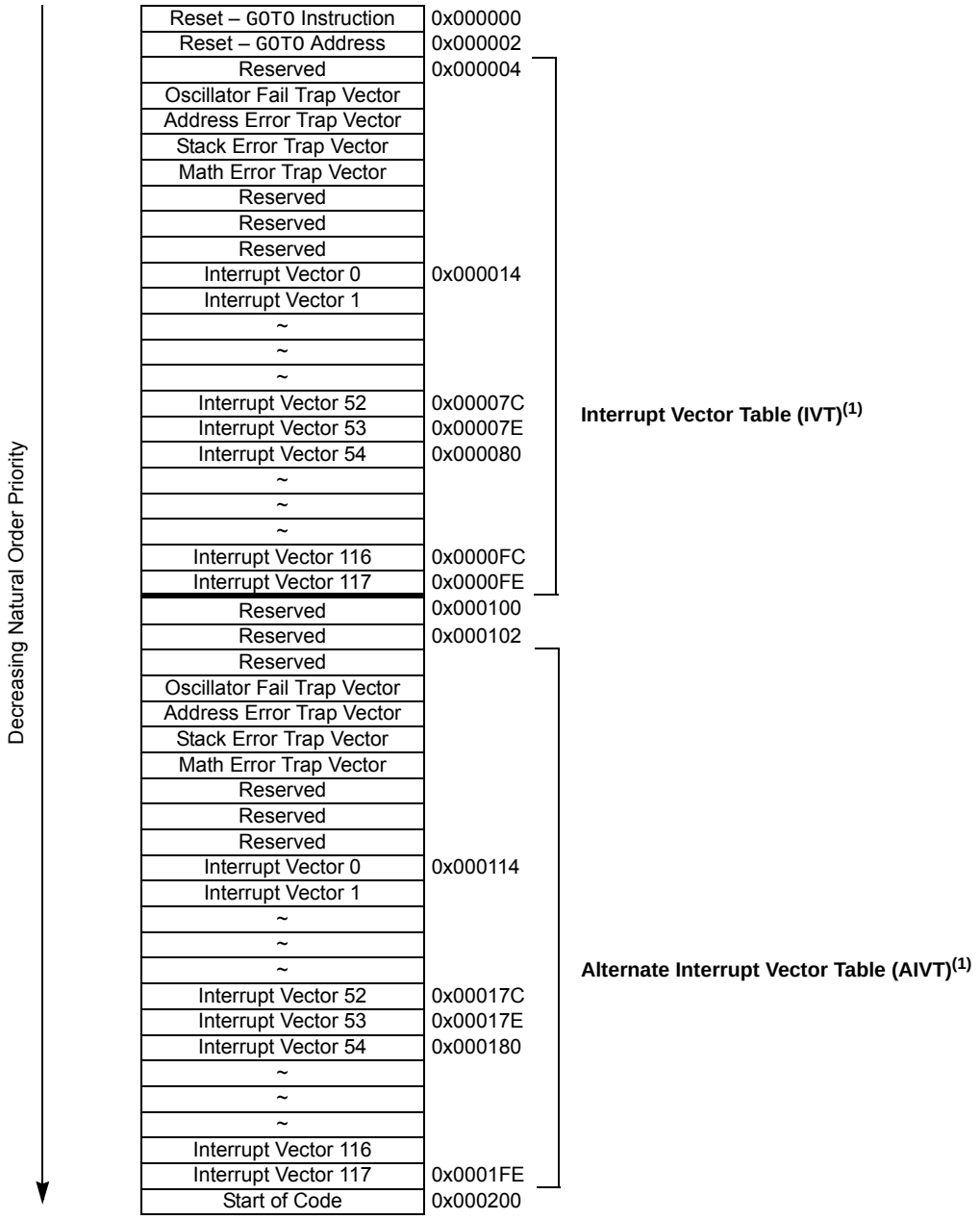
3.6.3 BARREL SHIFTER

The barrel shifter can perform up to 16-bit arithmetic or logic right shifts, or up to 16-bit left shifts in a single cycle. The source can be either of the two DSP accumulators or the X bus (to support multi-bit shifts of register or memory data).

The shifter requires a signed binary value to determine both the magnitude (number of bits) and direction of the shift operation. A positive value shifts the operand right. A negative value shifts the operand left. A value of '0' does not modify the operand.

The barrel shifter is 40 bits wide, thereby obtaining a 40-bit result for DSP shift operations and a 16-bit result for MCU shift operations. Data from the X bus is presented to the barrel shifter between bit positions 16 and 31 for right shifts, and between bit positions 0 and 16 for left shifts.

FIGURE 7-1: dsPIC33FJ12GP201/202 INTERRUPT VECTOR TABLE



Note 1: See Table 7-1 for the list of implemented interrupt vectors.

REGISTER 7-8: IEC0: INTERRUPT ENABLE CONTROL REGISTER 0

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	AD1IE	U1TXIE	U1RXIE	SPI1IE	SPI1EIE	T3IE
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
T2IE	OC2IE	IC2IE	—	T1IE	OC1IE	IC1IE	INT0IE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **AD1IE:** ADC1 Conversion Complete Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 12 **U1TXIE:** UART1 Transmitter Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 11 **U1RXIE:** UART1 Receiver Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 10 **SPI1IE:** SPI1 Event Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 9 **SPI1EIE:** SPI1 Error Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 8 **T3IE:** Timer3 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 7 **T2IE:** Timer2 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 6 **OC2IE:** Output Compare Channel 2 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 5 **IC2IE:** Input Capture Channel 2 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 4 **Unimplemented:** Read as '0'

bit 3 **T1IE:** Timer1 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 2 **OC1IE:** Output Compare Channel 1 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

TABLE 8-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>	Note
Fast RC Oscillator with Divide-by-N (FRCDIVN)	Internal	xx	111	**1, 2**
Fast RC Oscillator with Divide-by-16 (FRCDIV16)	Internal	xx	110	**1**
Low-Power RC Oscillator (LPRC)	Internal	xx	101	**1**
Secondary (Timer1) Oscillator (SOSC)	Secondary	xx	100	**1**
Primary Oscillator (HS) with PLL (HSPLL)	Primary	10	011	
Primary Oscillator (XT) with PLL (XTPLL)	Primary	01	011	
Primary Oscillator (EC) with PLL (ECPLL)	Primary	00	011	**1**
Primary Oscillator (HS)	Primary	10	010	
Primary Oscillator (XT)	Primary	01	010	
Primary Oscillator (EC)	Primary	00	010	**1**
Fast RC Oscillator with PLL (FRCPLL)	Internal	xx	001	**1**
Fast RC Oscillator (FRC)	Internal	xx	000	**1**

Note 1: OSC2 pin function is determined by the OSCIOFNC Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

REGISTER 8-3: PLLFBD: PLL FEEDBACK DIVISOR REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0(1)
—	—	—	—	—	—	—	PLLDIV<8>
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0
PLLDIV<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 8-0 **PLLDIV<8:0>:** PLL Feedback Divisor bits (also denoted as 'M', PLL multiplier)

111111111 = 513
•
•
•
000110000 = 50 (default)
•
•
•
000000010 = 4
000000001 = 3
000000000 = 2

Note 1: This register is reset only on a Power-on Reset (POR).

9.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the dsPIC33FJ12GP201/202 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 9. "Watchdog Timer and Power Savings Modes"** (DS70196) of the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJ12GP201/202 devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. dsPIC33FJ12GP201/202 devices can manage power consumption in four different ways:

- Clock frequency
- Instruction-based Sleep and Idle modes
- Software-controlled Doze mode
- Selective peripheral control in software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

9.1 Clock Frequency and Clock Switching

dsPIC33FJ12GP201/202 devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSC bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 8.0 "Oscillator Configuration"**.

9.2 Instruction-Based Power-Saving Modes

dsPIC33FJ12GP201/202 devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The Assembler syntax of the PWRSAV instruction is shown in Example 9-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out, or a device Reset. When the device exits these modes, it is said to wake-up.

9.2.1 SLEEP MODE

The following occur in Sleep mode:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current
- The Fail-Safe Clock Monitor does not operate, since the system clock source is disabled
- The LPRC clock continues to run if the WDT is enabled
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode
- Some device features or peripherals may continue to operate. This includes items such as the input change notification on the I/O ports, or peripherals that use an external clock input.
- Any peripheral that requires the system clock source for its operation is disabled

The device will wake-up from Sleep mode on any of the these events:

- Any interrupt source that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Sleep mode, the processor restarts with the same clock source that was active when Sleep mode was entered.

EXAMPLE 9-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV  #SLEEP_MODE    ; Put the device into Sleep mode
PWRSAV  #IDLE_MODE     ; Put the device into Idle mode
```

REGISTER 10-8: RPINR20: PERIPHERAL PIN SELECT INPUT REGISTER 20

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	SCK1R<4:0>				
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	SDI1R<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **SCK1R<4:0>:** Assign SPI1 Clock Input (SCK1IN) to the corresponding RPn pin bits

11111 = Input tied to Vss
01111 = Input tied to RP15
•
•
•
00001 = Input tied to RP1
00000 = Input tied to RP0

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **SDI1R<4:0>:** Assign SPI1 Data Input (SDI1) to the corresponding RPn pin bits

11111 = Input tied to Vss
01111 = Input tied to RP15
•
•
•
00001 = Input tied to RP1
00000 = Input tied to RP0

REGISTER 10-11: RPOR1: PERIPHERAL PIN SELECT OUTPUT REGISTERS 1

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP3R<4:0>				
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP2R<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-8 **RP3R<4:0>:** Peripheral Output Function is Assigned to RP3 Output Pin bits (see Table 10-2 for peripheral function numbers)

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4-0 **RP2R<4:0>:** Peripheral Output Function is Assigned to RP2 Output Pin bits (see Table 10-2 for peripheral function numbers)

REGISTER 10-12: RPOR2: PERIPHERAL PIN SELECT OUTPUT REGISTERS 2

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP5R<4:0>				
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP4R<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-8 **RP5R<4:0>:** Peripheral Output Function is Assigned to RP5 Output Pin bits (see Table 10-2 for peripheral function numbers)

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4-0 **RP4R<4:0>:** Peripheral Output Function is Assigned to RP4 Output Pin bits (see Table 10-2 for peripheral function numbers)

13.0 INPUT CAPTURE

Note 1: This data sheet summarizes the features of the dsPIC33FJ12GP201/202 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 12. "Input Capture"** (DS70198) of the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Input Capture module is useful in applications requiring frequency (period) and pulse measurement. The dsPIC33FJ12GP201/202 devices support up to eight input capture channels.

The Input Capture module captures the 16-bit value of the selected Time Base register when an event occurs at the ICx pin. The events that cause a capture event are listed below in three categories:

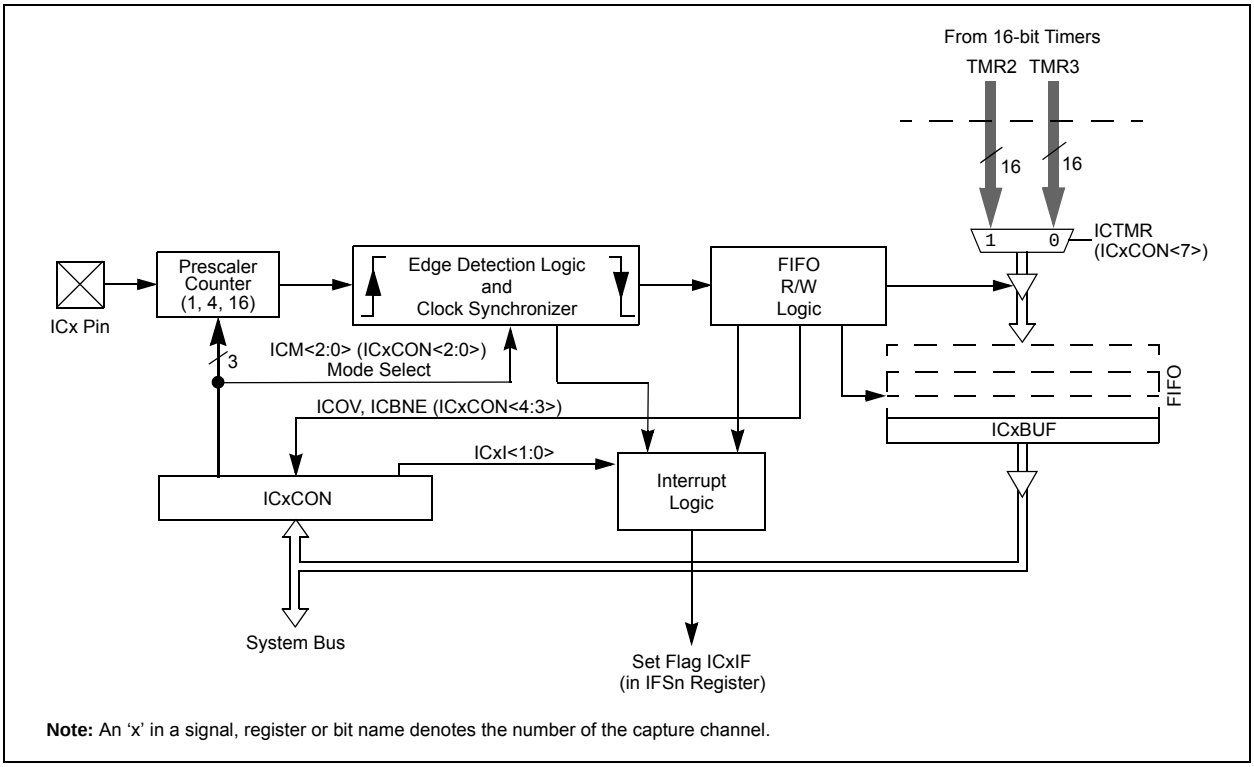
- Simple Capture Event modes:
  - Capture timer value on every falling edge of input at ICx pin
  - Capture timer value on every rising edge of input at ICx pin
- Capture timer value on every edge (rising and falling)
- Prescaler Capture Event modes:
  - Capture timer value on every 4th rising edge of input at ICx pin
  - Capture timer value on every 16th rising edge of input at ICx pin

Each Input Capture channel can select one of two 16-bit timers (Timer2 or Timer3) for the time base. The selected timer can use either an internal or external clock.

Other operational features include:

- Device wake-up from capture pin during CPU Sleep and Idle modes
- Interrupt on Input Capture event
- 4-word FIFO buffer for capture values
  - Interrupt optionally generated after 1, 2, 3, or 4 buffer locations are filled
- Use of Input Capture to provide additional

FIGURE 13-1: INPUT CAPTURE BLOCK DIAGRAM



Note: An 'x' in a signal, register or bit name denotes the number of the capture channel.

REGISTER 15-1: SPIxSTAT: SPIx STATUS AND CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
SPIEN	—	SPISIDL	—	—	—	—	—
bit 15							bit 8

U-0	R/C-0	U-0	U-0	U-0	U-0	R-0	R-0
—	SPIROV	—	—	—	—	SPITBF	SPIRBF
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **SPIEN:** SPIx Enable bit
1 = Enables module and configures SCKx, SDOx, SDIx, and $\overline{SSx}$ as serial port pins
0 = Disables module

bit 14 **Unimplemented:** Read as '0'

bit 13 **SPISIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when device enters Idle mode
0 = Continue module operation in Idle mode

bit 12-7 **Unimplemented:** Read as '0'

bit 6 **SPIROV:** Receive Overflow Flag bit
1 = A new byte/word is completely received and discarded. The user software has not read the previous data in the SPIxBUF register.
0 = No overflow has occurred.

bit 5-2 **Unimplemented:** Read as '0'

bit 1 **SPITBF:** SPIx Transmit Buffer Full Status bit
1 = Transmit not yet started, SPIxTXB is full
0 = Transmit started, SPIxTXB is empty
Automatically set in hardware when CPU writes SPIxBUF location, loading SPIxTXB
Automatically cleared in hardware when SPIx module transfers data from SPIxTXB to SPIxSR

bit 0 **SPIRBF:** SPIx Receive Buffer Full Status bit
1 = Receive complete, SPIxRXB is full
0 = Receive is not complete, SPIxRXB is empty
Automatically set in hardware when SPIx transfers data from SPIxSR to SPIxRXB
Automatically cleared in hardware when core reads SPIxBUF location, reading SPIxRXB

19.2 On-Chip Voltage Regulator

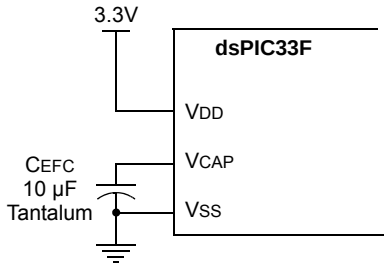
The dsPIC33FJ12GP201/202 devices power their core digital logic at a nominal 2.5V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, both devices in the dsPIC33FJ12GP201/202 family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. When the regulator is enabled, a low ESR (less than 5 ohms) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 19-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 22-13 located in **Section 22.1 "DC Characteristics"**.

Note:	It is important for low-ESR capacitors to be placed as close as possible to the VCAP pin.

On a POR, it takes approximately 20 μs for the on-chip voltage regulator to generate an output voltage. During this time, designated as TSTARTUP, code execution is disabled. TSTARTUP is applied every time the device resumes operation after any power-down.

FIGURE 19-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR(1,2,3)



Note 1: These are typical operating voltages. Refer to Table 22-13 located in **Section 22.1 "DC Characteristics"** for the full operating ranges of VDD and VCAP.

2: It is important for low-ESR capacitors to be placed as close as possible to the VCAP pin.

3: Typical VCAP pin voltage = 2.5V when VDD ≥ VDDMIN.

19.3 BOR Module

The BOR module is based on an internal voltage reference circuit that monitors the regulated voltage VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines, or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the PWRT time-out (TPWRT) will be applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, a nominal delay of TFSCM = 100 is applied. The total delay in this case is TFSCM.

The BOR Status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle modes and resets the device should VDD fall below the BOR threshold voltage.

TABLE 22-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

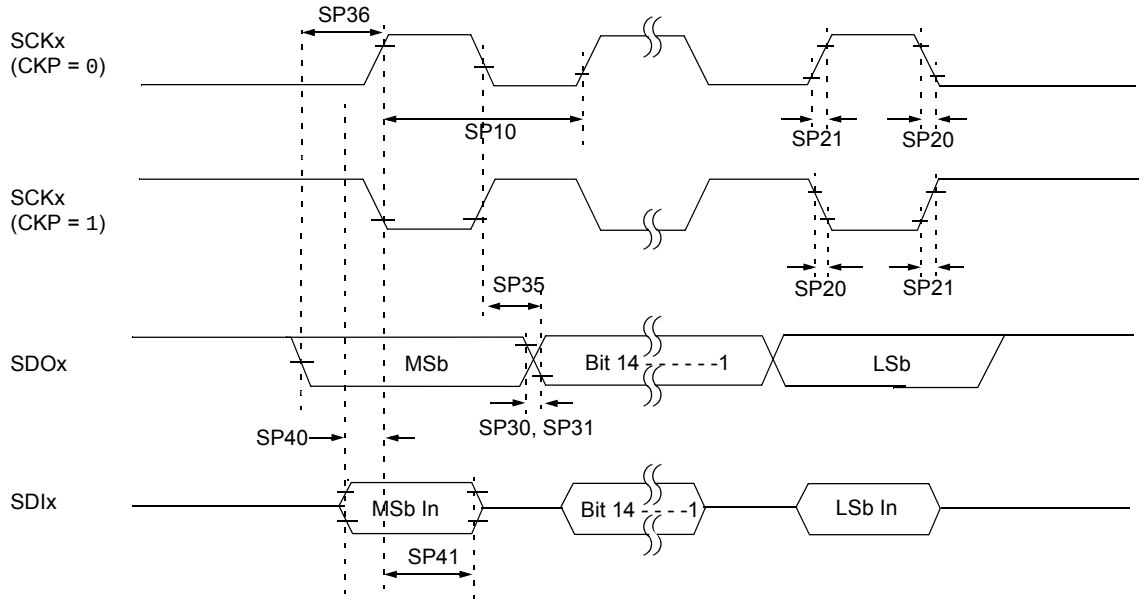
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
Operating Voltage							
DC10	**Supply Voltage**						
	VDD		3.0	—	3.6	V	Industrial and Extended
DC12	VDR	**RAM Data Retention Voltage(2)**	1.8	—	—	V	
DC16	VPOR	**VDD Start Voltage(3)** to ensure internal Power-on Reset signal	—	—	VSS	V	
DC17	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.03	—	—	V/ms	0-3.0V in 0.1s

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: This is the limit to which VDD can be lowered without losing RAM data.

3: VDD voltage must remain at Vss for a minimum of 200 µs to ensure POR.

FIGURE 22-11: SPIx MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = X, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 22-1 for load conditions.

TABLE 22-30: SPIx MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP10	TscP	Maximum SCK Frequency	—	—	9	MHz	See **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—

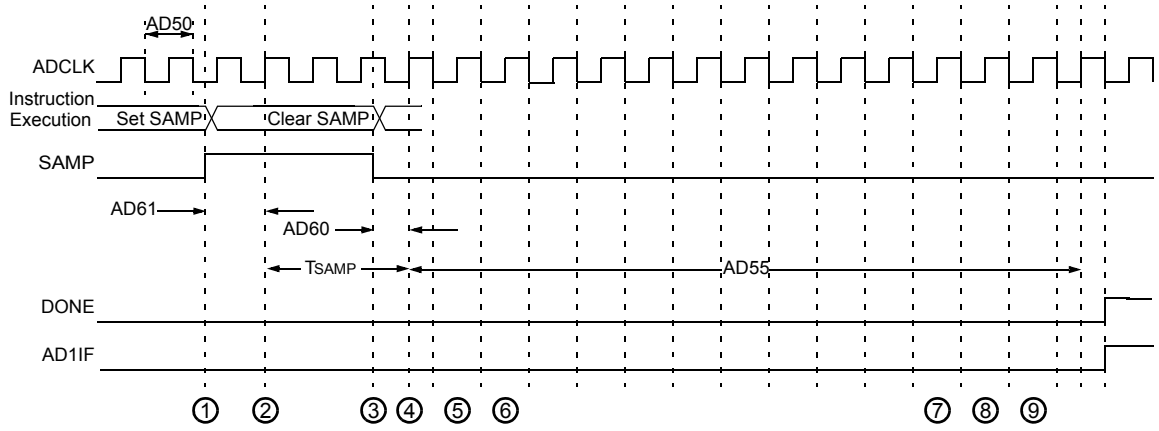
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 111 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 22-21: ADC CONVERSION (12-BIT MODE) TIMING CHARACTERISTICS (ASAM = 0, SSRC<2:0> = 000)



1 – Software sets AD1CON. SAMP to start sampling.
2 – Sampling starts after discharge period. TSAMP is described in **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33F/PIC24H Family Reference Manual*.
3 – Software clears AD1CON. SAMP to start conversion.
4 – Sampling ends, conversion sequence starts.
5 – Convert bit 11.
6 – Convert bit 10.
7 – Convert bit 1.
8 – Convert bit 0.
9 – One TAD for end of conversion.

TABLE 22-41: ADC CONVERSION (12-BIT MODE) TIMING REQUIREMENTS

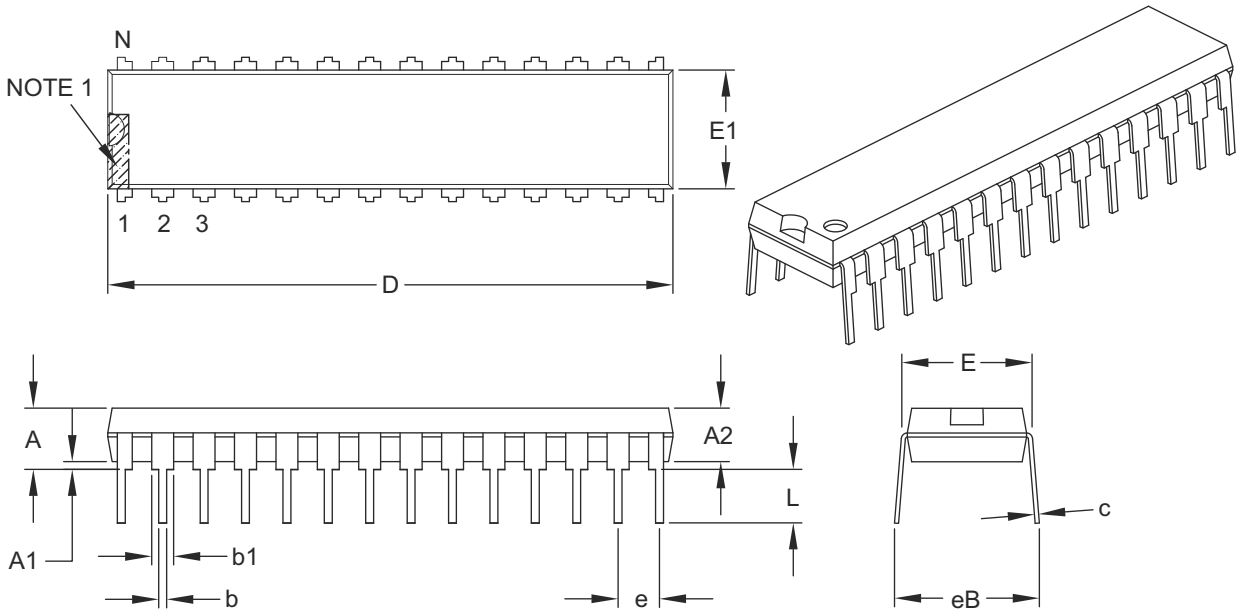
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
Clock Parameters(1)							
AD50	TAD	ADC Clock Period	117.6	—	—	ns	
AD51	tRC	ADC Internal RC Oscillator Period	—	250	—	ns	
Conversion Rate							
AD55	tCONV	Conversion Time	—	14 TAD		ns	
AD56	FCNV	Throughput Rate	—	—	500	Ksps	
AD57	TSAMP	Sample Time	3.0 TAD	—	—	—	
Timing Parameters							
AD60	tPCS	Conversion Start from Sample Trigger(2)	2.0 TAD	—	3.0 TAD	—	Auto Convert Trigger not selected
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit(2)	2.0 TAD	—	3.0 TAD	—	—
AD62	tCSS	Conversion Completion to Sample Start (ASAM = 1)(2)	—	0.5 TAD	—	—	—
AD63	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(2)	—	—	20	μs	—

Note 1: Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.

2: These parameters are characterized but not tested in manufacturing.

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

TABLE 23-1: MAJOR SECTION UPDATES

Section Name	Update Description
Section 22.0 "Electrical Characteristics"	Updated Max MIPS value for -40ºC to +125ºC temperature range in Operating MIPS vs. Voltage (see Table 22-1). Added 28-pin SSOP package information to Thermal Packaging Characteristics and updated Typical values for all devices (see Table 22-3). Removed Typ value for parameter DC12 (see Table 22-4). Updated Note 2 in Table 22-7: DC Characteristics: Power-Down Current (I_{PD}). Updated MIPS conditions for parameters DC24c, DC44c, DC72a, DC72f, and DC72g (see Table 22-5, Table 22-6, and Table 22-8). Added Note 4 (reference to new table containing digital-only and analog pin information to I/O Pin Input Specifications (see Table 22-9). Updated Program Memory parameters (D136a, D136b, D137a, D137b, D138a, and D138b) and added Note 2 (see Table 22-12). Updated Max value for Internal RC Accuracy parameter F21 for -40°C ≤T_A ≤ +125°C condition and added Note 2 (see Table 22-19). Removed all values for Reset, Watchdog Timer, Oscillator Start-up Timer, and Power-up Timer parameter SY20 and updated conditions, which now refers to **Section 19.4 "Watchdog Timer (WDT)"** and LPRC parameter F21 (see Table 22-21). The following changes were made to the ADC Module Specifications (Table 22-34): • Updated Min value for ADC Module Specification parameter AD07 • Updated Typ value for parameter AD08 • Removed parameter AD10 • Added references to Note 1 for parameters AD12 and AD13 • Removed Note 2. The following changes were made to the ADC Module Specifications (12-bit Mode) (Table 22-35): • Updated Min and Max values for both AD21a parameters (measurements with *internal* and *external* V_{REF+}/V_{REF-}). • Updated Min, Typ, and Max values for parameter AD24a. • Updated Max value for parameter AD32a. • Removed Note 1. • Removed V_{REFL} from Conditions for parameters AD21a, AD22a, AD23a, and AD24a (measurements with *internal* V_{REF+}/V_{REF-}). The following changes were made to the ADC Module Specifications (10-bit Mode) (Table 22-36): • Updated Min and Max values for parameter AD21b (measurements with *external* V_{REF+}/V_{REF-}). • Removed ± symbol from Min, Typ, and Max values for parameters AD23b and AD24b (measurements with *internal* V_{REF+}/V_{REF-}). • Updated Typ and Max values for parameter AD32b. • Removed Note 1. • Removed V_{REFL} from Conditions for parameters AD21a, AD22a, AD23a, and AD24a (measurements with *internal* V_{REF+}/V_{REF-}). Updated Min and Typ values for parameters AD60, AD61, AD62, and AD63 and removed Note 3 (see Table 22-37 and Table 22-38).

Worldwide Sales and Service

AMERICAS

Corporate Office
2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200
Fax: 480-792-7277
Technical Support:
http://www.microchip.com/support
Web Address:
www.microchip.com

Atlanta
Duluth, GA
Tel: 678-957-9614
Fax: 678-957-1455

Boston
Westborough, MA
Tel: 774-760-0087
Fax: 774-760-0088

Chicago
Itasca, IL
Tel: 630-285-0071
Fax: 630-285-0075

Cleveland
Independence, OH
Tel: 216-447-0464
Fax: 216-447-0643

Dallas
Addison, TX
Tel: 972-818-7423
Fax: 972-818-2924

Detroit
Farmington Hills, MI
Tel: 248-538-2250
Fax: 248-538-2260

Indianapolis
Noblesville, IN
Tel: 317-773-8323
Fax: 317-773-5453

Los Angeles
Mission Viejo, CA
Tel: 949-462-9523
Fax: 949-462-9608

Santa Clara
Santa Clara, CA
Tel: 408-961-6444
Fax: 408-961-6445

Toronto
Mississauga, Ontario, Canada
Tel: 905-673-0699
Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office
Suites 3707-14, 37th Floor
Tower 6, The Gateway
Harbour City, Kowloon
Hong Kong
Tel: 852-2401-1200
Fax: 852-2401-3431

Australia - Sydney
Tel: 61-2-9868-6733
Fax: 61-2-9868-6755

China - Beijing
Tel: 86-10-8569-7000
Fax: 86-10-8528-2104

China - Chengdu
Tel: 86-28-8665-5511
Fax: 86-28-8665-7889

China - Chongqing
Tel: 86-23-8980-9588
Fax: 86-23-8980-9500

China - Hangzhou
Tel: 86-571-2819-3180
Fax: 86-571-2819-3189

China - Hong Kong SAR
Tel: 852-2401-1200
Fax: 852-2401-3431

China - Nanjing
Tel: 86-25-8473-2460
Fax: 86-25-8473-2470

China - Qingdao
Tel: 86-532-8502-7355
Fax: 86-532-8502-7205

China - Shanghai
Tel: 86-21-5407-5533
Fax: 86-21-5407-5066

China - Shenyang
Tel: 86-24-2334-2829
Fax: 86-24-2334-2393

China - Shenzhen
Tel: 86-755-8203-2660
Fax: 86-755-8203-1760

China - Wuhan
Tel: 86-27-5980-5300
Fax: 86-27-5980-5118

China - Xian
Tel: 86-29-8833-7252
Fax: 86-29-8833-7256

China - Xiamen
Tel: 86-592-2388138
Fax: 86-592-2388130

China - Zhuhai
Tel: 86-756-3210040
Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore
Tel: 91-80-3090-4444
Fax: 91-80-3090-4123

India - New Delhi
Tel: 91-11-4160-8631
Fax: 91-11-4160-8632

India - Pune
Tel: 91-20-2566-1512
Fax: 91-20-2566-1513

Japan - Yokohama
Tel: 81-45-471- 6166
Fax: 81-45-471-6122

Korea - Daegu
Tel: 82-53-744-4301
Fax: 82-53-744-4302

Korea - Seoul
Tel: 82-2-554-7200
Fax: 82-2-558-5932 or
82-2-558-5934

Malaysia - Kuala Lumpur
Tel: 60-3-6201-9857
Fax: 60-3-6201-9859

Malaysia - Penang
Tel: 60-4-227-8870
Fax: 60-4-227-4068

Philippines - Manila
Tel: 63-2-634-9065
Fax: 63-2-634-9069

Singapore
Tel: 65-6334-8870
Fax: 65-6334-8850

Taiwan - Hsin Chu
Tel: 886-3-6578-300
Fax: 886-3-6578-370

Taiwan - Kaohsiung
Tel: 886-7-213-7830
Fax: 886-7-330-9305

Taiwan - Taipei
Tel: 886-2-2500-6610
Fax: 886-2-2508-0102

Thailand - Bangkok
Tel: 66-2-694-1351
Fax: 66-2-694-1350

EUROPE

Austria - Wels
Tel: 43-7242-2244-39
Fax: 43-7242-2244-393

Denmark - Copenhagen
Tel: 45-4450-2828
Fax: 45-4485-2829

France - Paris
Tel: 33-1-69-53-63-20
Fax: 33-1-69-30-90-79

Germany - Munich
Tel: 49-89-627-144-0
Fax: 49-89-627-144-44

Italy - Milan
Tel: 39-0331-742611
Fax: 39-0331-466781

Netherlands - Drunen
Tel: 31-416-690399
Fax: 31-416-690340

Spain - Madrid
Tel: 34-91-708-08-90
Fax: 34-91-708-08-91

UK - Wokingham
Tel: 44-118-921-5869
Fax: 44-118-921-5820

05/02/11